

# An Advanced Probe Characterization Tool for Online Contact Basics Measurements

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Oliver Nagler (Infineon Technologies AG, Munich, Germany)

Markus Reinl, Prof. Dr. Ignaz Eisele (Universität der Bundeswehr, Munich, Germany)



Never stop thinking.

# An Advanced Probe Characterization Tool

## Outline

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- Motivation
- Existing Tools
- Schematic
- Realisation
- Components
- Calibration
- Exemplary Measurements
- Summary
- Outlook

# An Advanced Probe Characterization Tool

## Motivation

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- Modelling contact basics
- Optimizing contact resistance
- Avoiding oxide / low-k crack generation
- Influence of vertical and lateral forces wrt Cres
- Investigation of pad materials (thickness, hardness, etc.)
- Analysis of oxide films
- Evaluating new probe types
- Investigating prober dynamics

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## Existing Tools for Contact Force Measurement

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- Single Probe Plunger in Probe Card Analyser
- Weighing Platform (only z-force)
- Piezoresistive force sensor in Probe Holder
- Micromechanical sensors
- Pad-integrated sensors
- Automatic Prober

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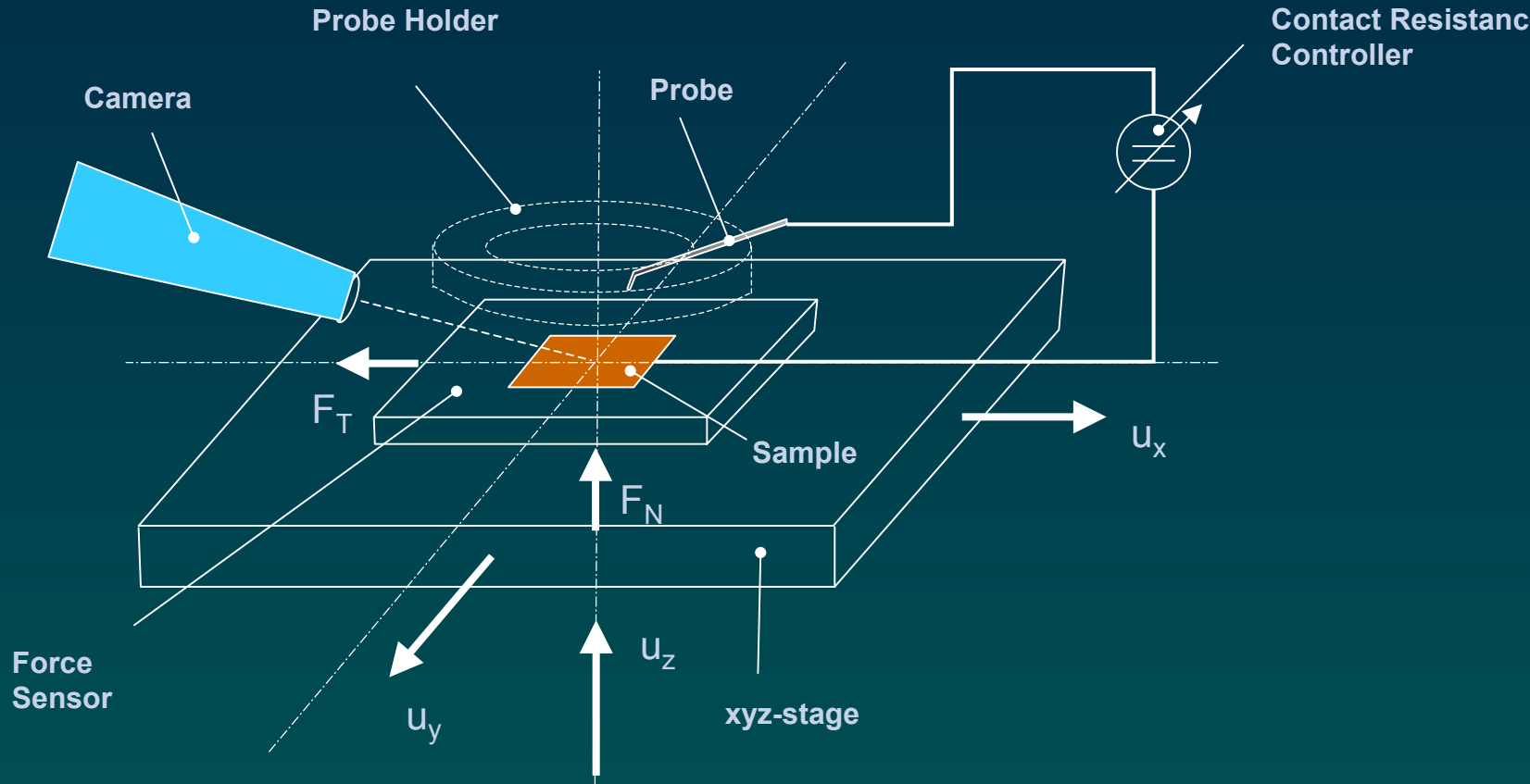
## Requirement Specification

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1. Realtime contact resistance measurements
2. Automatic contact point definition
3. Positioning Accuracy in ...  
xy-direction:  $\pm 0.5 \mu\text{m}$   
z-direction:  $\pm 0.05 \mu\text{m}$
3. Capable for mounting different probe card types
4. Simultaneous sensing of lateral and vertical forces in the range of 0.5mN .... 10 N
5. Retainer for various samples (Al, Cu, SiO<sub>2</sub>, chips, ...)
6. Static and dynamic measurements
7. Microscope w/ video camera
8. Optional test under variable environment gas (O<sub>2</sub>, N<sub>2</sub>, ...)
9. Optional test with variable probing temperature (-40 - 125°C)

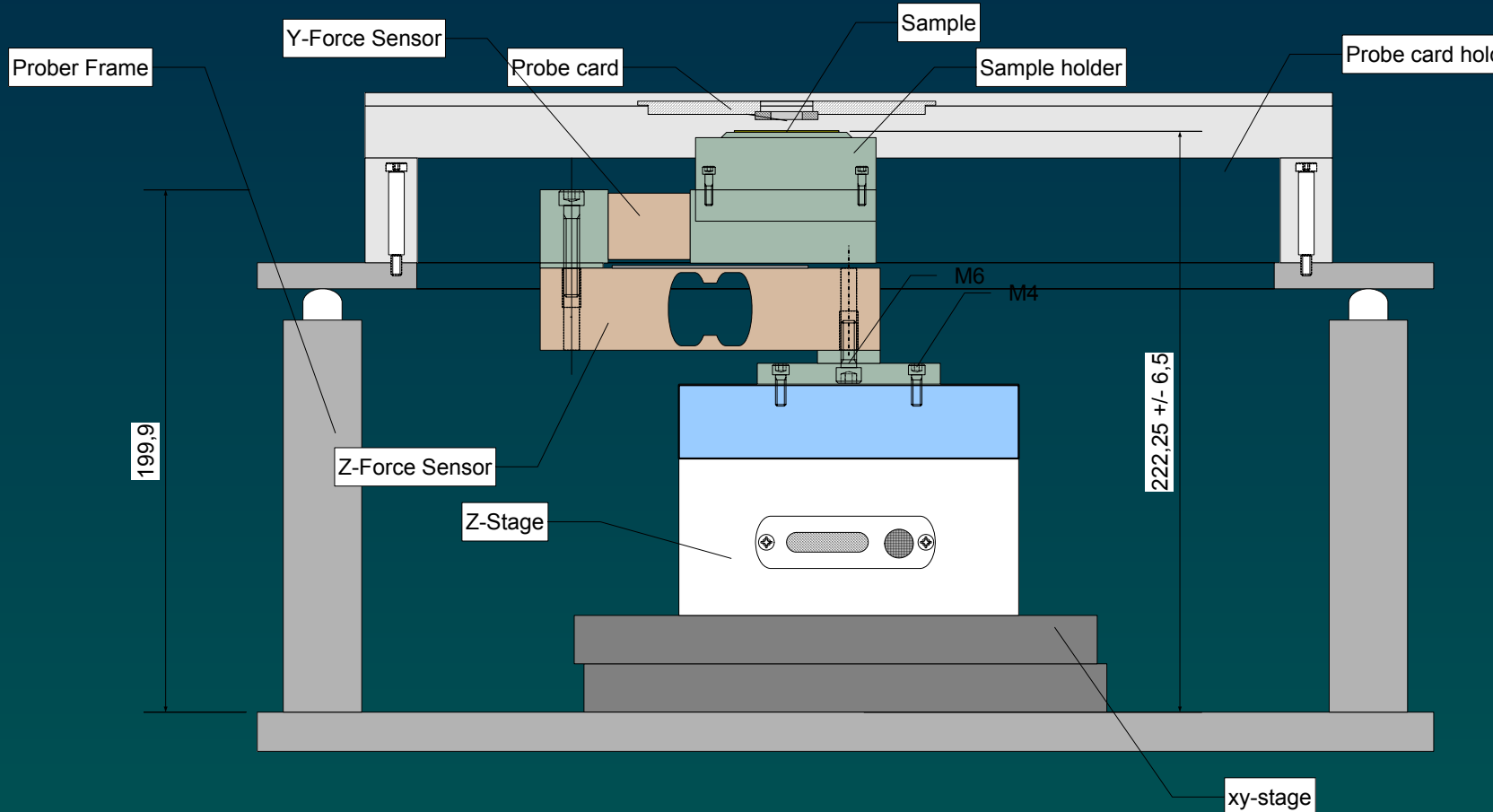
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## Tool Schematic



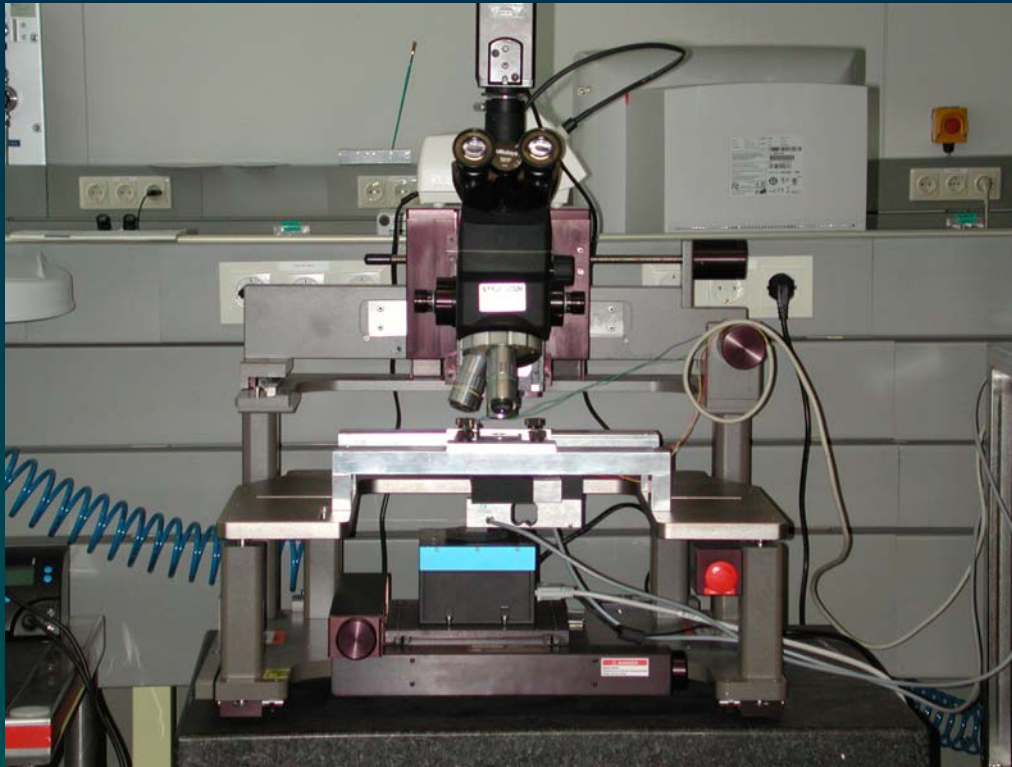
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## Manufacturing Drawing



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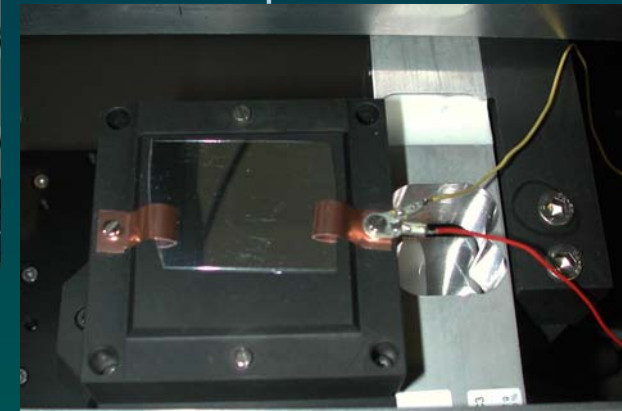
## General View



## Single-Probe Card



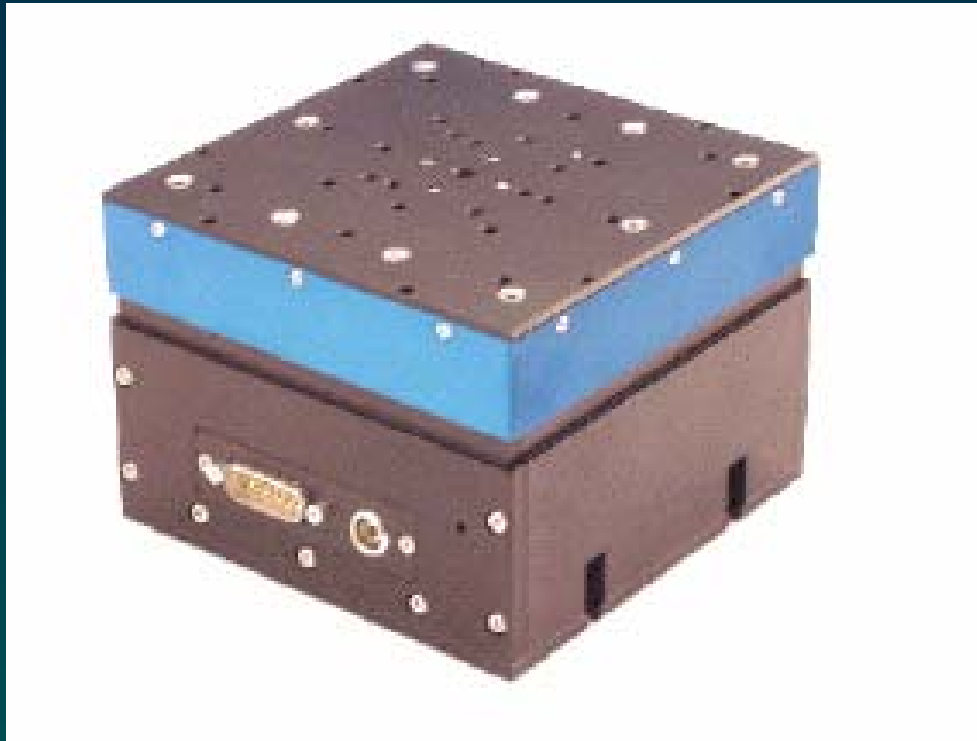
## Sample Holder





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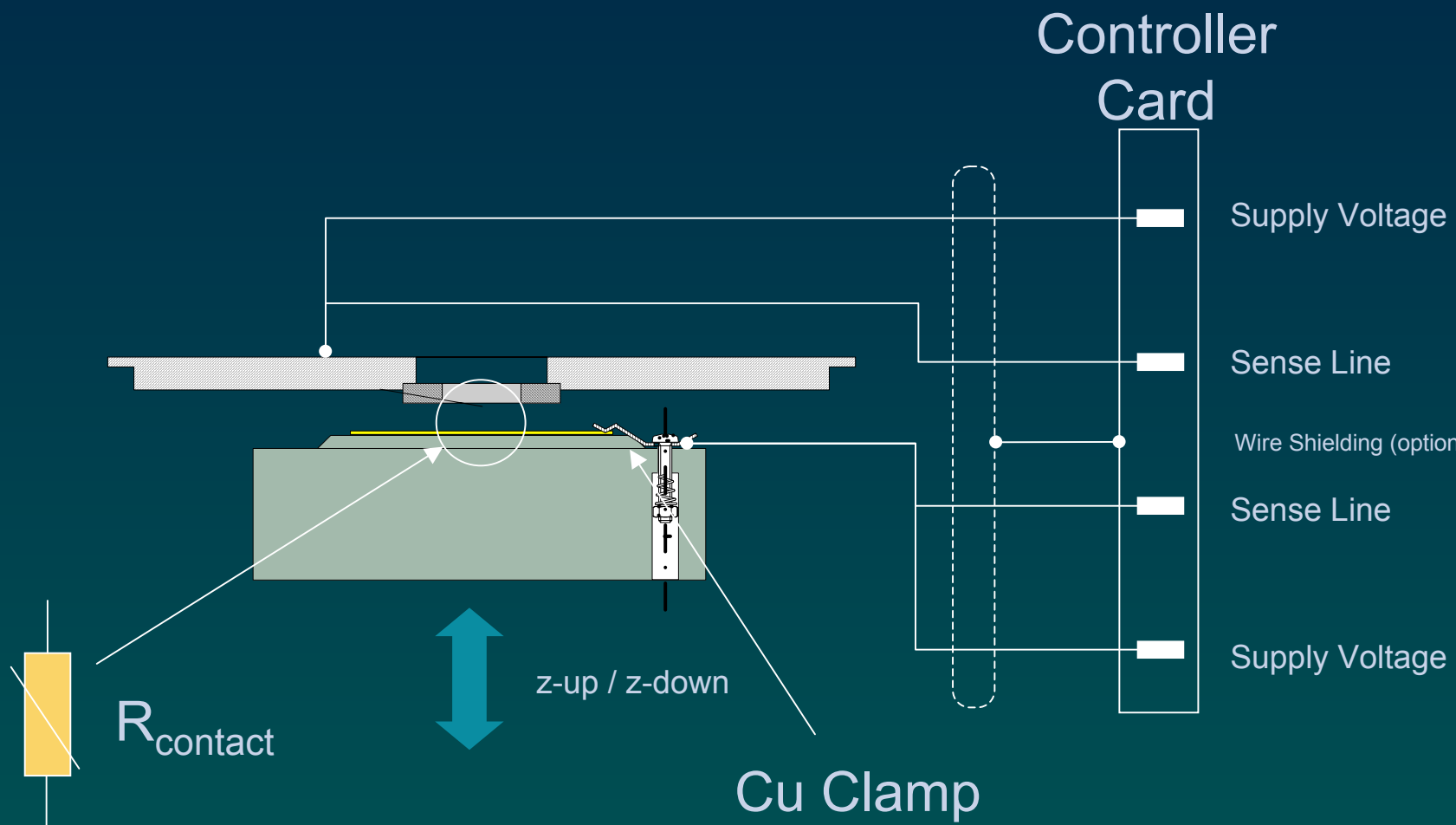
## Vertical Positioning Stage



Travel range	12.5	mm
Design resolution	0.024	$\mu\text{m}$
Min. incremental motion	<0.1	$\mu\text{m}$
Unidirectional repeatability	0.1	$\mu\text{m}$
Max. velocity	12	mm/sec
Max. normal load capacity	5	kg
Max. holding force (motor off)	20	N
Encoder resolution	40,960*	cts/rev
Ballscrew pitch	1	mm/rev
Gear ratio	80/26 (belt drive)	
Nominal motor power	17**	W
Motor voltage range	0 to $\pm 24$	V
Weight		
Body material	Al	

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## 4-pole Cres Measurement



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## Single Point x- and z-Load Cell

Special Feature: Off center load compensated

Type		PW2GC3				
Accuracy class		C3 <sup>1)</sup>				
Maximum number of load cell intervals ( $n_{LC}$ )		3000				
Maximum capacity ( $E_{max}$ )	kg	7.2	12	18	36	72
Minimum LC verification interval ( $v_{min}$ )	g	2	2	5	10	20
Maximum platform size	mm	380 x 380				
Sensitivity ( $C_n$ )	mV/V	2.4 ± 0.24				
Zero balance (without dead load)	mV/V	0 ± 0.1				

Absolute Accuracy:

x-direction: 21,6 mN

z-direction: 36 mN

Resolution:

x-direction : 0,36 mN

z-direction : 0,6 mN



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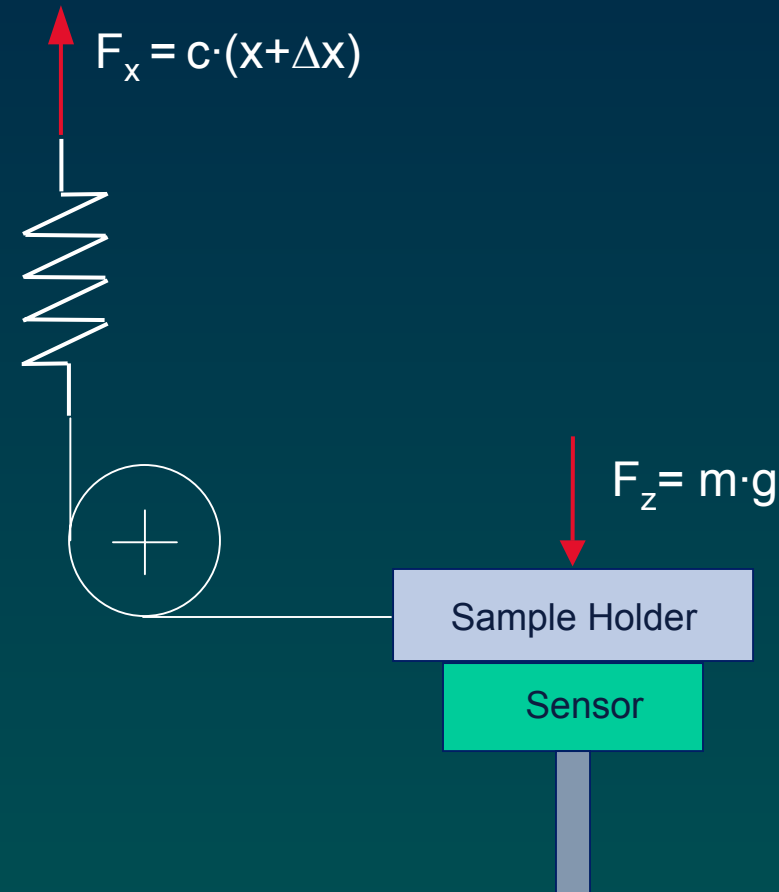
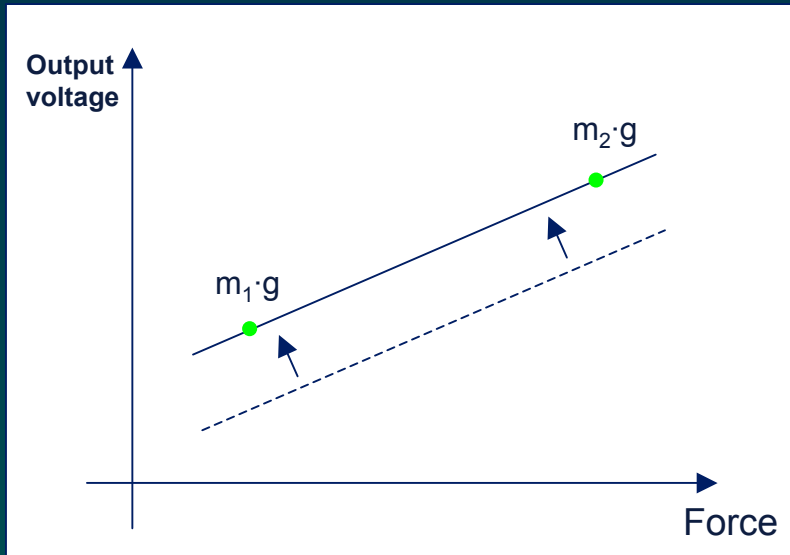
## Data Acquisition and Visualisation

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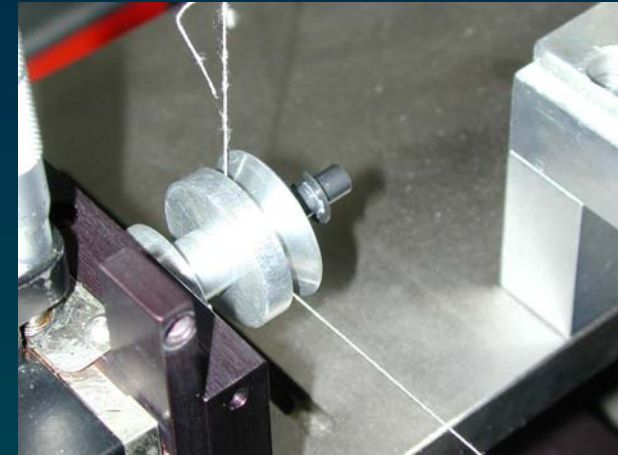
- Software Options:
  - Automatic amplifier recognition
  - Sensor database available and expandable
  - Graphical display
  - Real-time
  - Different interfaces supported (USB, Ethernet, GPIB, etc.)
  - MS Windows XP
  - Measurement data exported in commonly used formats (e.g. ASCII, EXCEL, ....)

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## Calibration Method



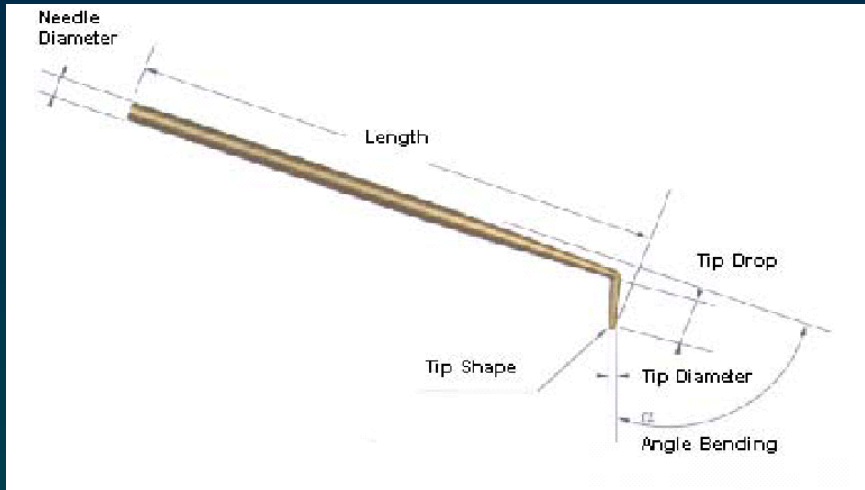
# An Advanced Probe Characterization Tool Calibration Realisation



## Exemplary Measurements with a Cantilever Probe

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## Cantilever Probe used for Demonstration

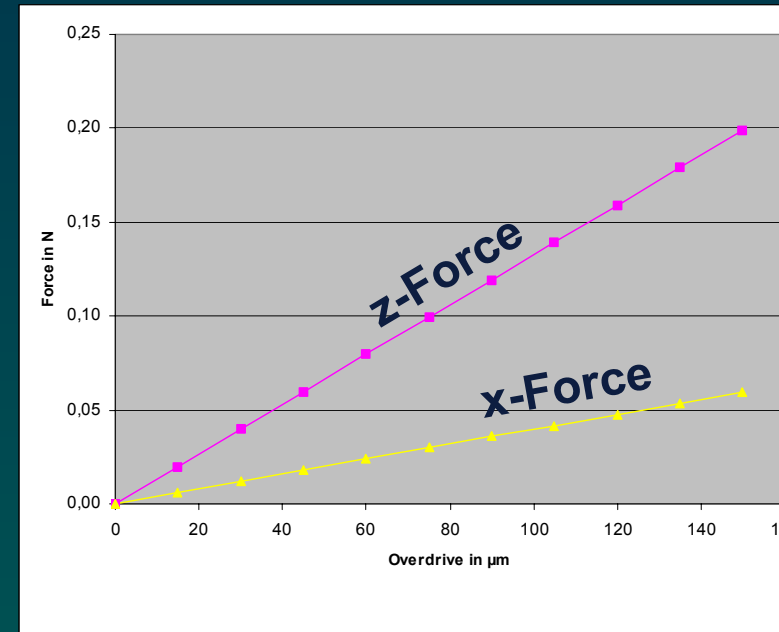


Approximation of Probe Pressure

$$W = \frac{3\pi \beta D^4 E \delta}{64L^3} \text{ (N)}$$

Definitions:  
 W: Probe pressure (g), L: Beam length (mm),  
 D: Probe diameter,  $\delta$ : Overdrive amount (mm),  
 E: Young's modulus (N/mm<sup>2</sup>),  
 $\beta$ : Attenuation constant depending on tapers and shapes.

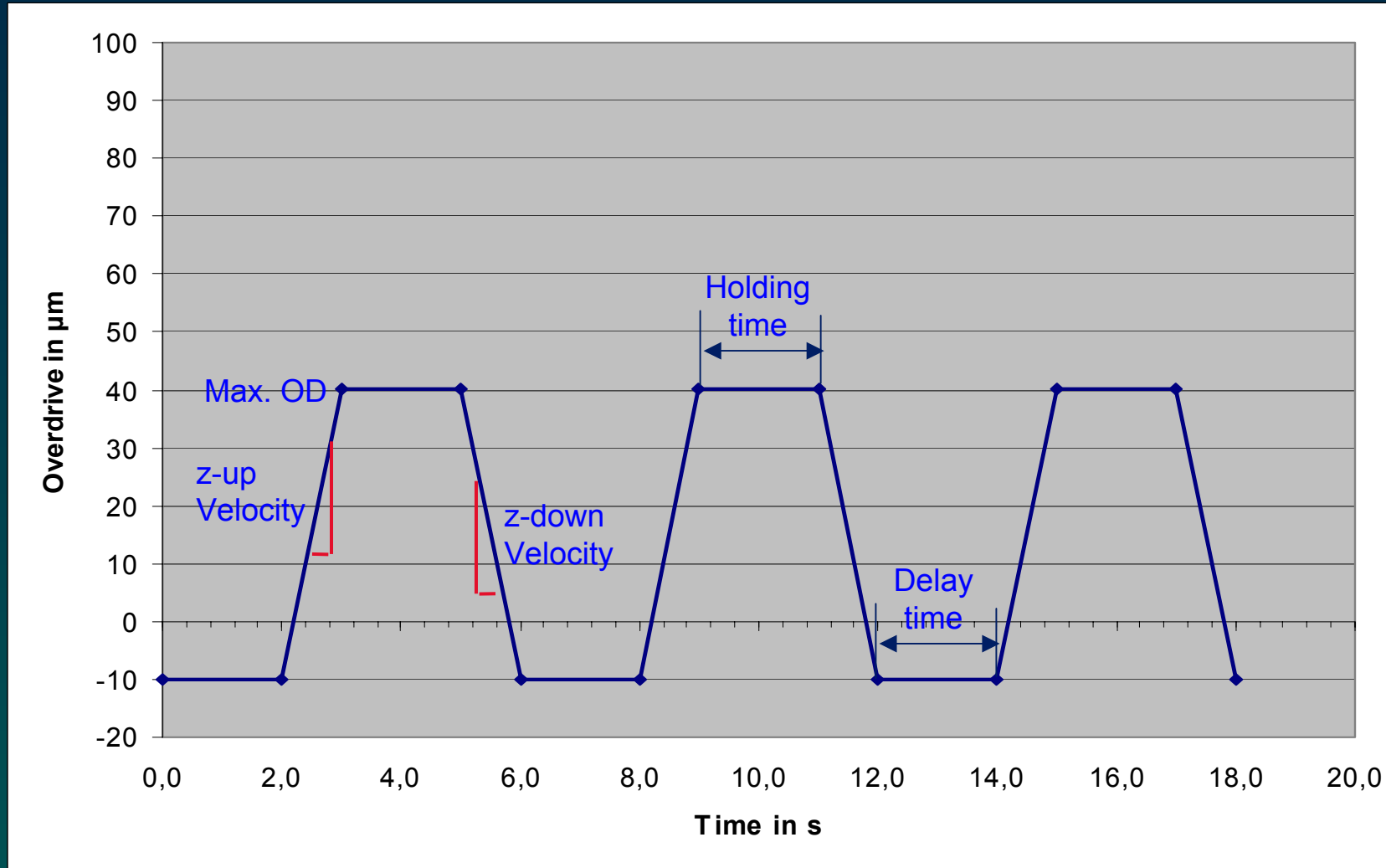
Source: MJC





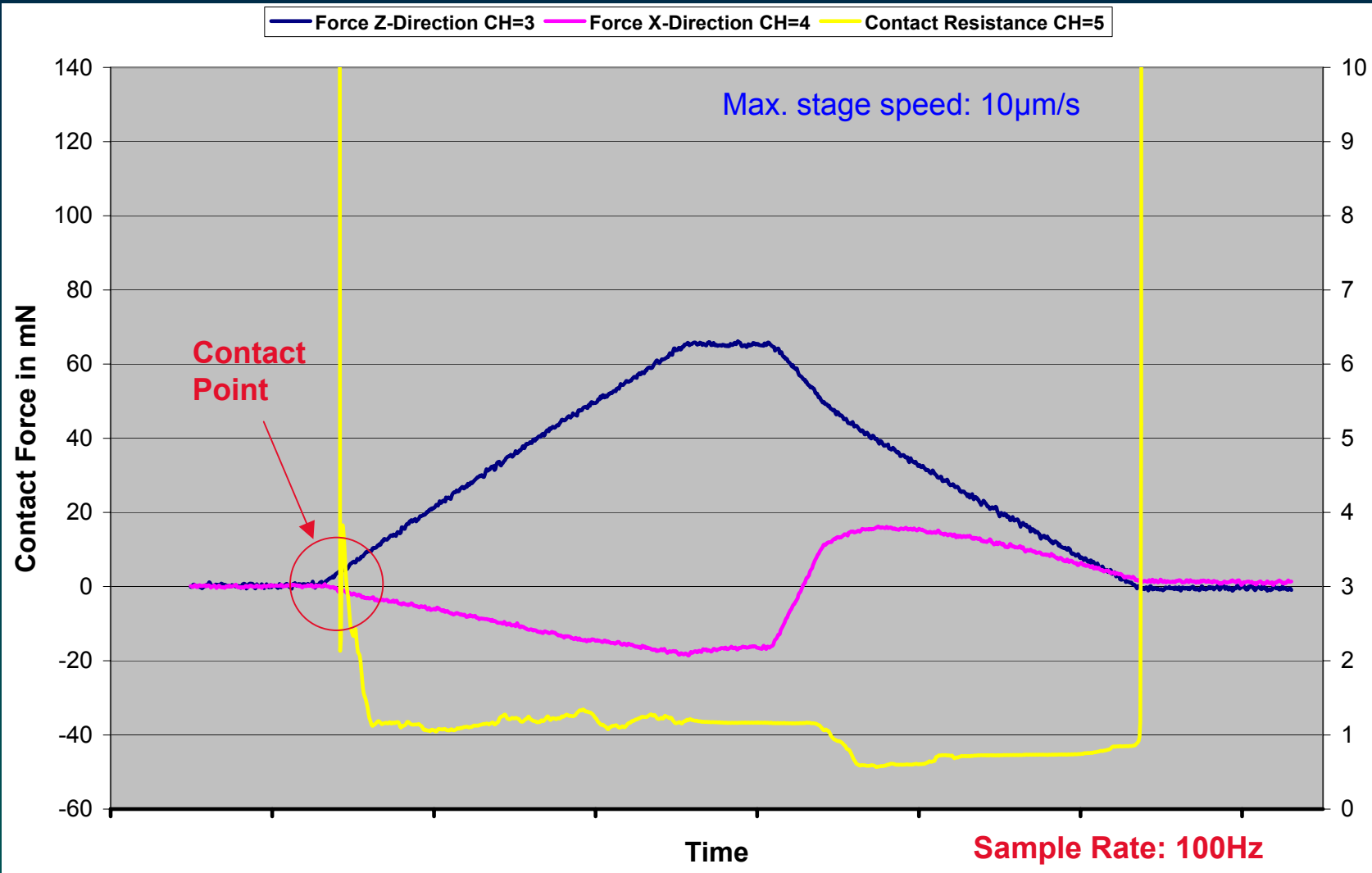
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## z-Stage Profile



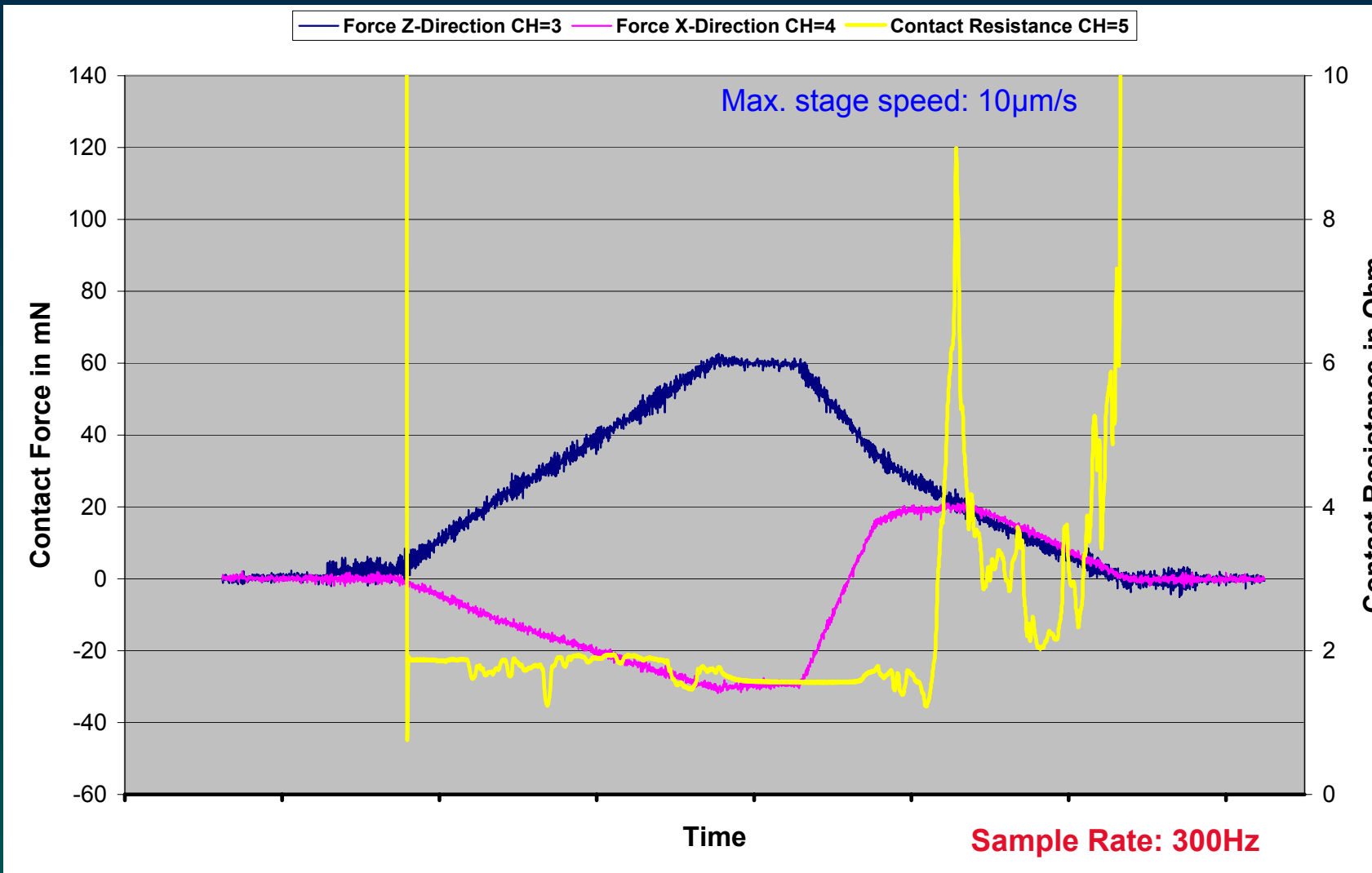
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## Measurement on Gold Wafer (max. OD = 50 $\mu$ m)



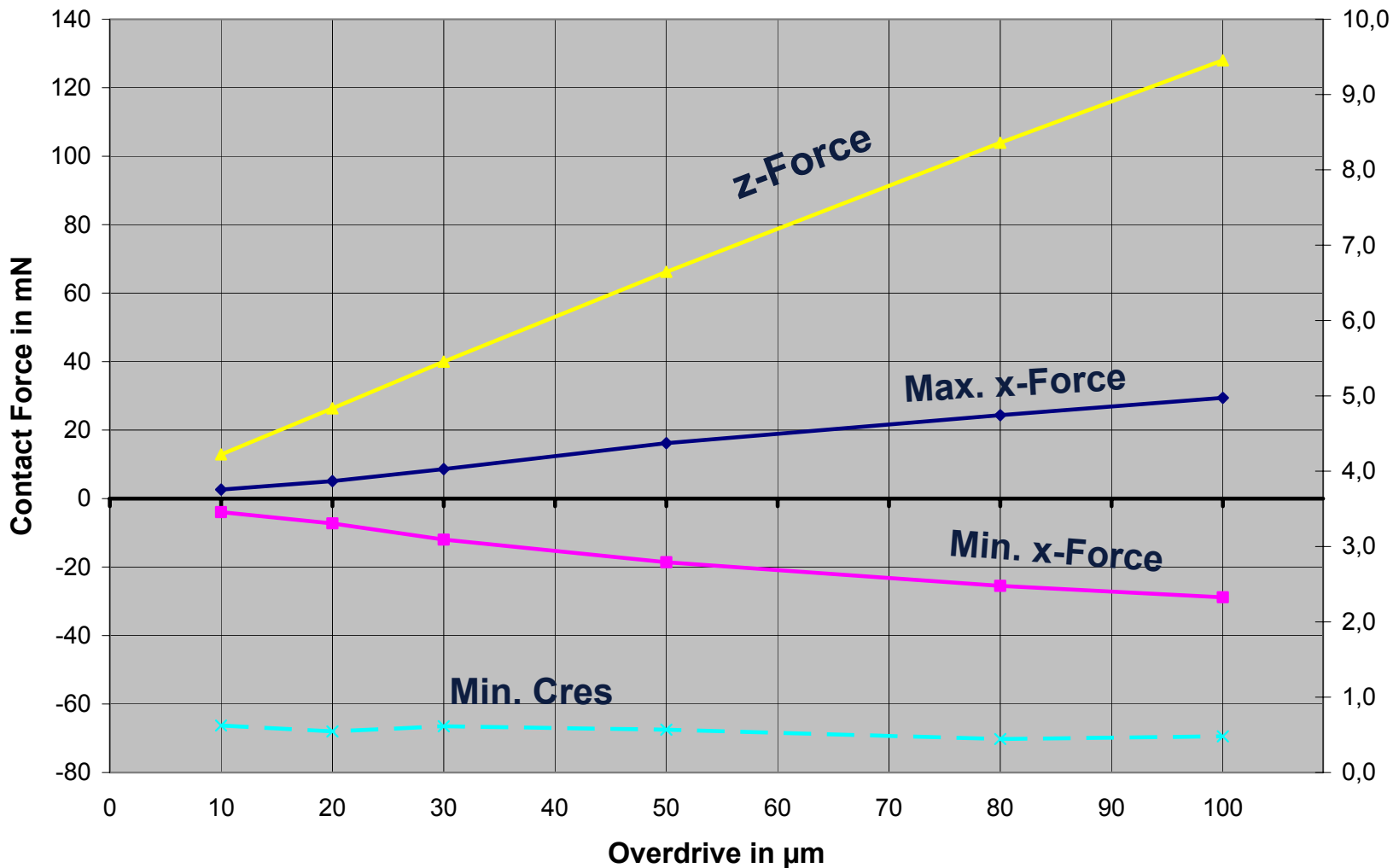
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## Measurement on Aluminum Wafer (max. OD = 50 $\mu$ m)



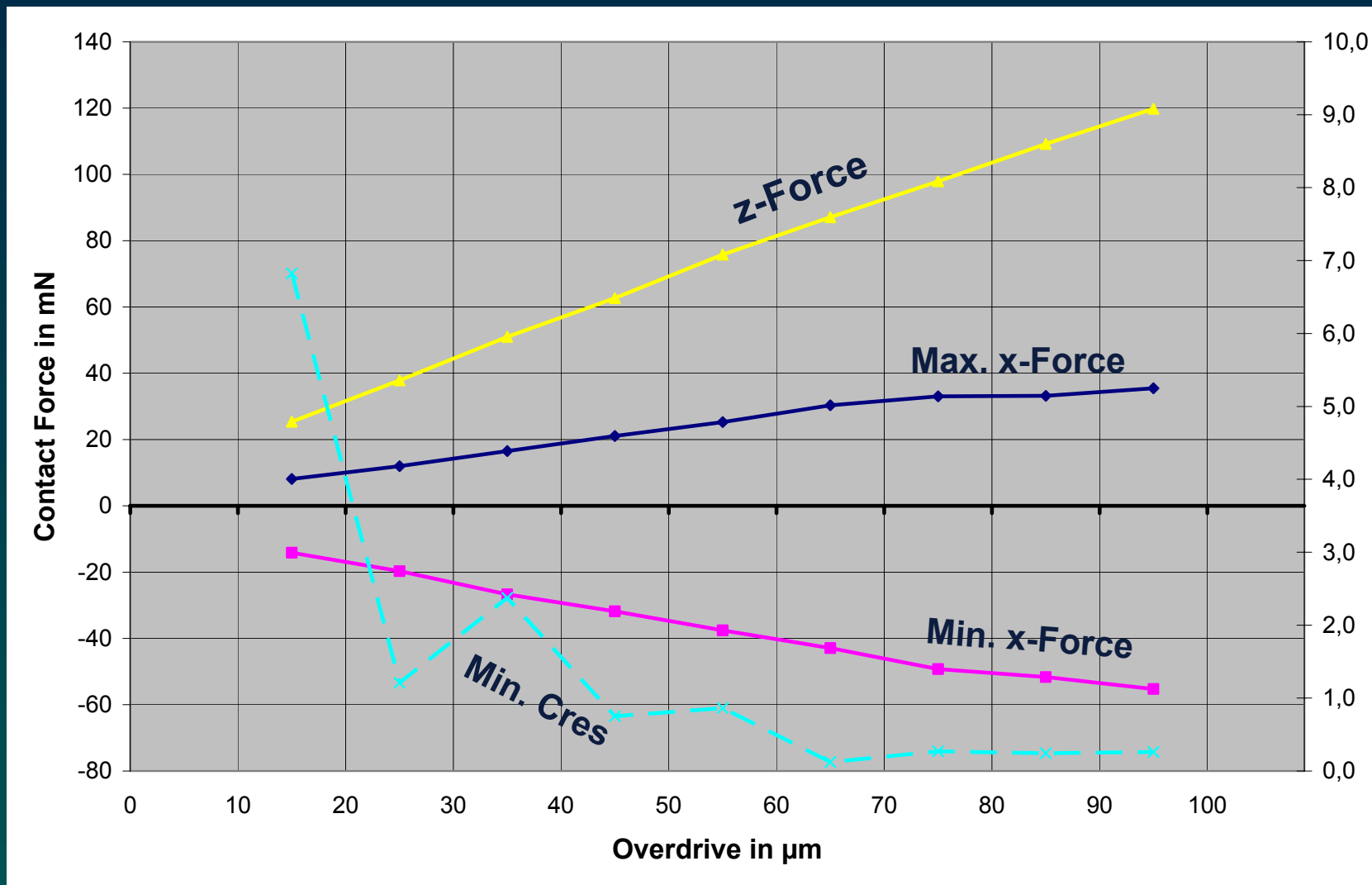
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## Probe Parameters vs. OD on Gold



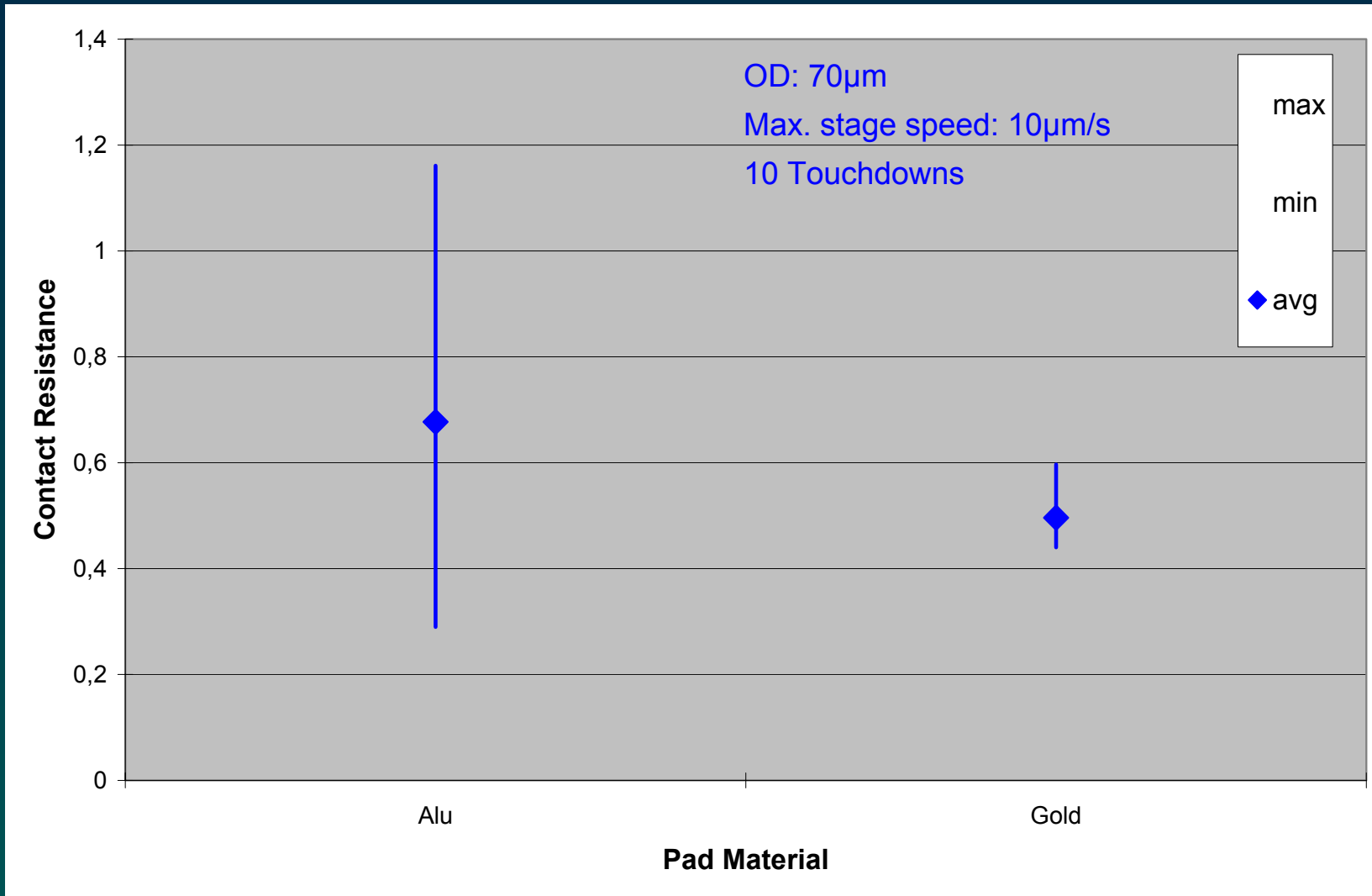
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## Probe Parameters vs. OD on Aluminum



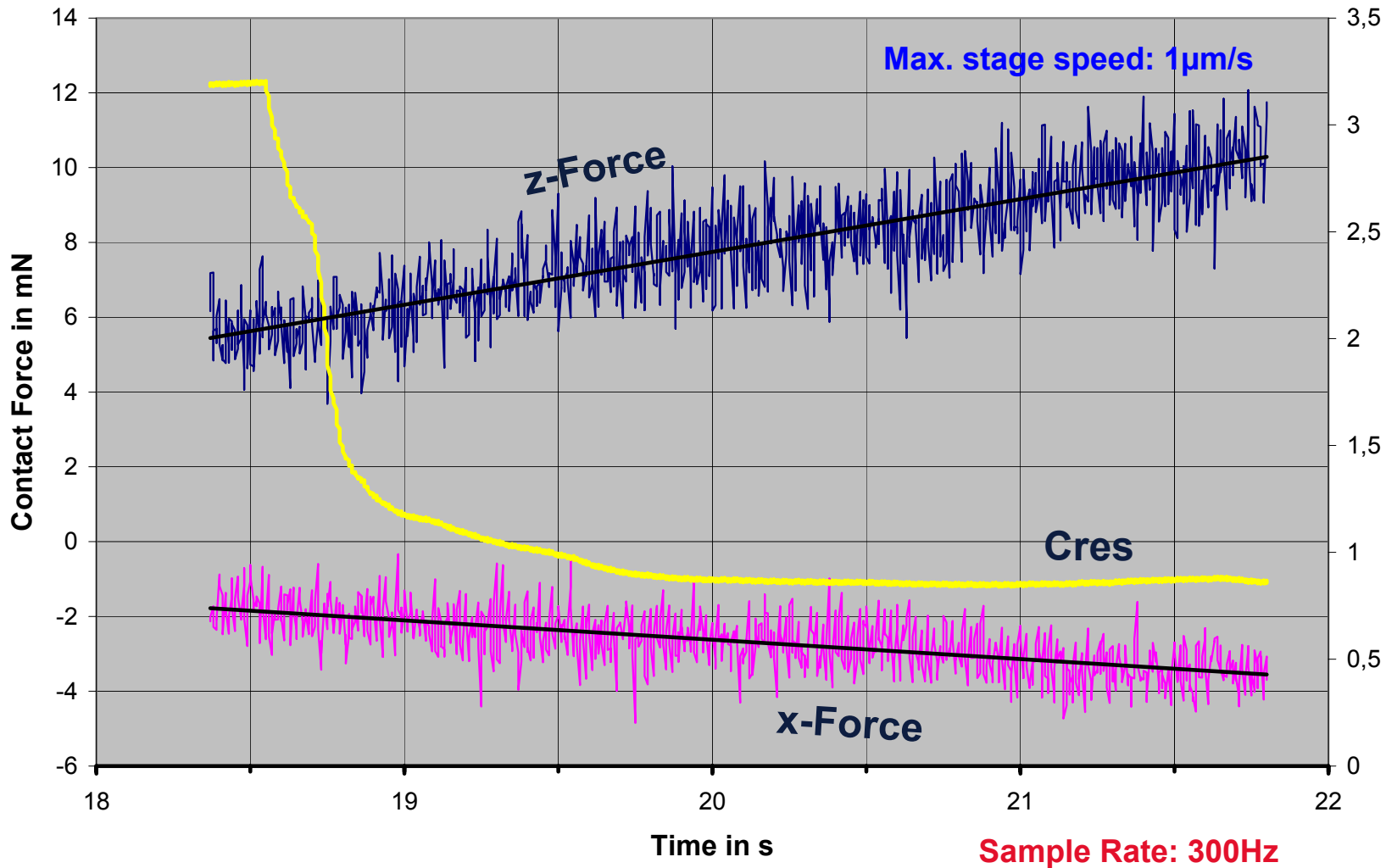
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## Cres Distribution



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## Quasi-Statical Measurement on Gold



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## Summary

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- A novel tool was demonstrated real-time measurements of lateral, vertical forces and contact resistance
- External noise must be minimized to improve accuracy
- Capable to all probing technologies
- Preliminary results show, that ...
  - Contact resistance on Au more stable than on Al (Oxide Film?)
  - Change of sign of lateral force during z-up/-down for cantilever probe
  - Coefficient of friction between 0.2 and 0.5 (material dependent)
  - Average  $C_{res}$  and distribution on Au smaller than on Al
  - Holm Theory to be verified



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## Next Steps

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- Elimination of disturbing factors (cabling, acoustic noise, ESD, vibrations)
- Labview Programming of z-stage
- Image processing software for microscope
- Verification of contact resistance model („Holm Theory“)
- Investigation of different probe types (vertical, MEMS, etc...)
- Influence of dynamics
- Analysis of new pad materials
- Oxide / low-k crack generation and avoidance
- Automated x- and y-stage control